



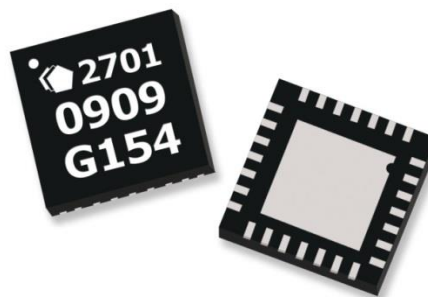
TGA2701-SM

3 Watt C-Band Power Amplifier

General Description

The Qorvo TGA2701-SM is a packaged 35 dBm Power Amplifier for C-band applications. The TGA2701-SM provides a nominal 35 dBm of output power at an input power level of 22 dBm with a small signal gain of 18 dB. Nominal TOI is 42 dBm and noise figure is 7.5 dB.

The TGA2701-SM is an overmold QFN 6 x 6 mm surface mount package. It is ideally suited for low cost emerging markets such as point to point radio and communications.



Product Features

- Frequency Range: 5.9–9.0 GHz
- Saturation Power: 35 dBm
- P1dB: 34 dBm
- Gain: 18 dB
- TOI: 42 dBm
- PAE: 37%
- NF: 7.5 dB
- Bias: $V_D = 6\text{ V}$, $I_D = 1.0\text{ A}$, $V_G = -0.6\text{ V}$ Typical
- Package Dimensions: 6 x 6 x 0.85 mm

Applications

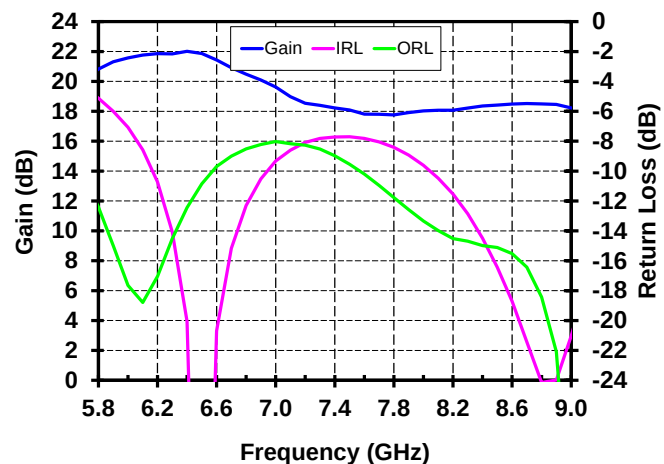
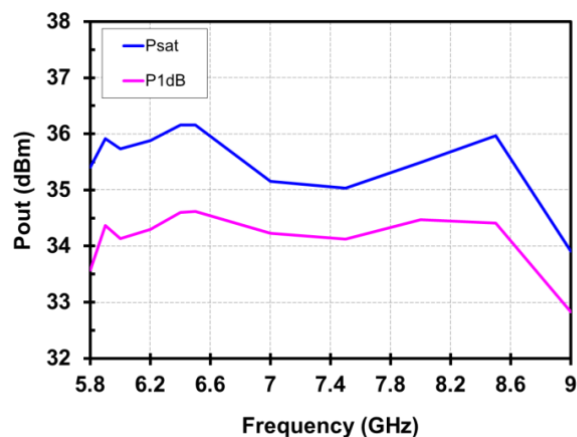
- Point-to-Point Radio
- Communications

Ordering Information

Part	Description
TGA2701-SM	Power Amplifier, Shipping Tray, Qty 50
TGA2701-SMEVB	TGA2701-SM Evaluation Board, Qty 1

Measured Performance

Bias conditions: $V_D = 6\text{ V}$, $I_D = 1.0\text{ A}$, $V_G = -0.6\text{ V}$ Typical



Absolute Maximum Ratings 1/

Symbol	Parameter	Value/Range	Notes
V_{D-V_G}	Drain to Gate Voltage	9.2 V	
V_D	Drain Voltage	8 V	2/
V_G	Gate Voltage Range	-1.2 to +0.5 V	
I_D	Drain Current	3.85 A	2/
I_G	Gate Current Range	-14 to 126 mA	
P_{IN}	Input Continuous Wave Power	29 dBm	
T-channel	Channel Temperature	200 °C	2/

Notes:

1. These ratings represent the maximum operable values for this device. Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device and / or affect device lifetime. These are stress ratings only, and functional operation of the device at these conditions is not implied.
2. Combinations of supply voltage, supply current, input power, and output power shall not exceed the maximum power dissipation listed in Table IV

Recommended Operating Conditions

Symbol	Parameter 1/	Value/Range
V_D	Drain Voltage	6 V
I_{DQ}	Drain Current	1.0 A
I_D Drive	Drain Current under RF Drive	1.6 A
V_G	Gate Voltage	-0.6 V

Notes:

1. See assembly diagram for bias instructions.

Electrical Specifications

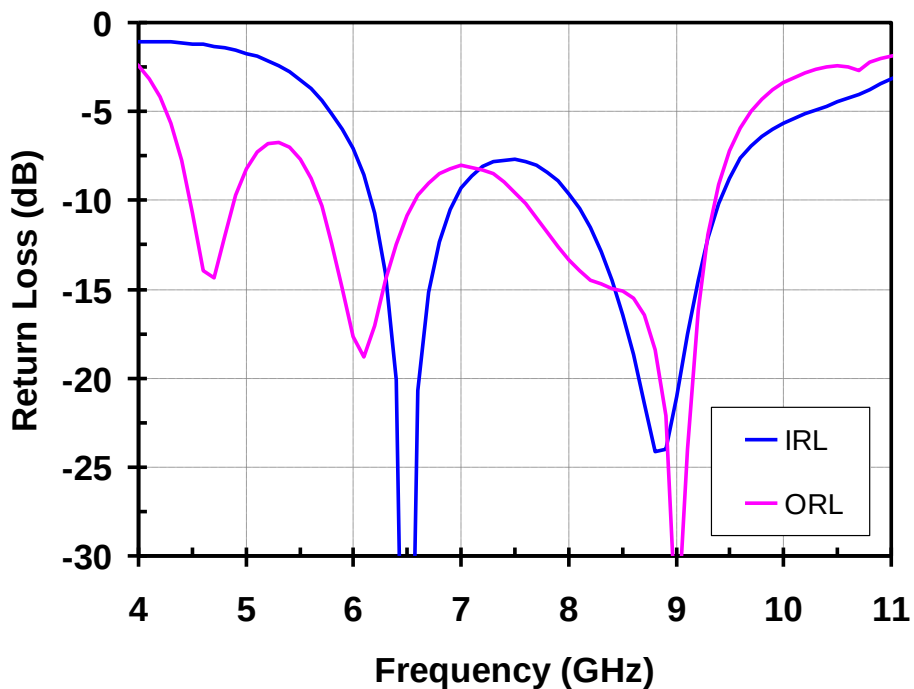
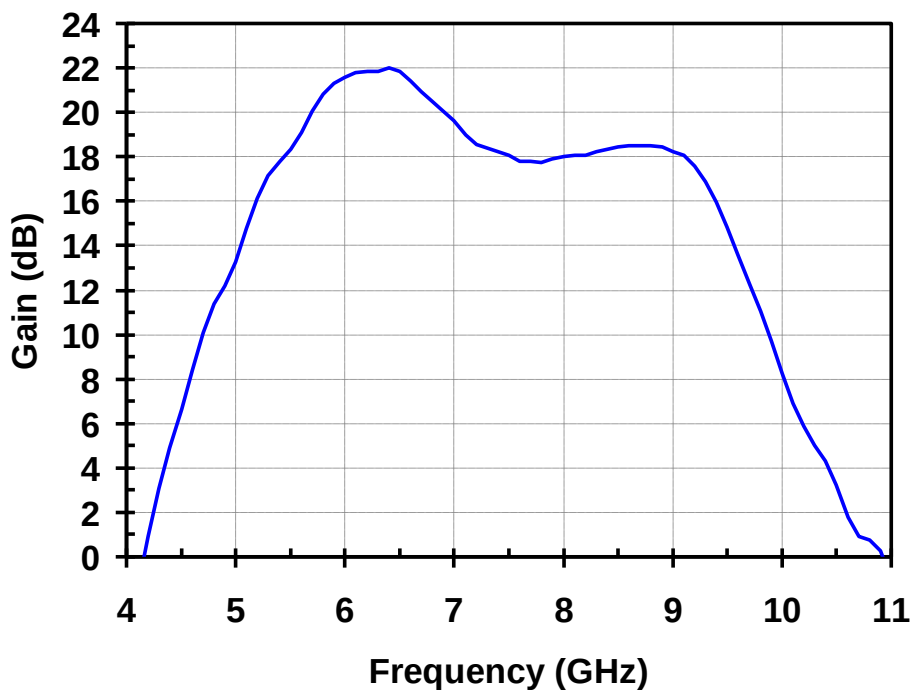
Bias: $V_D = 6$ V, $I_D = 1.0$ A, $V_G = -0.6$ V Typical, 25 °C

Data are de-embedded to reference lines

	Parameter	Test Conditions	Min	Normal	Max	Units
Gain	Small Signal Gain	F = 5.9 – 9 GHz	16	18	22	dB
IRL	Input Return Loss	F = 5.9 – 9 GHz		-10		dB
ORL	Output Return Loss	F = 5.9 – 9 GHz		-10		dB
P_{SAT}	Saturated Output Power	F = 5.9 – 8.5 GHz F = 9 GHz	34 33	35 34		dBm
P1dB	Output Power @ 1dB Compression	F = 5.9 – 9 GHz		34		dBm
TOI	Output TOI	F = 5.9 – 8.5 GHz F = 9 GHz Pout = 20 dBm/tone	39 37	42 40		dBm
NF	Noise Figure	F = 5.9 – 9 GHz		7.5		dB
	Gain Temperature Coefficient	F = 5.9 – 9 GHz		-0.03		dB/°C
	Power Temperature Coefficient	F = 5.9 – 9 GHz		-0.01		dBm/°C

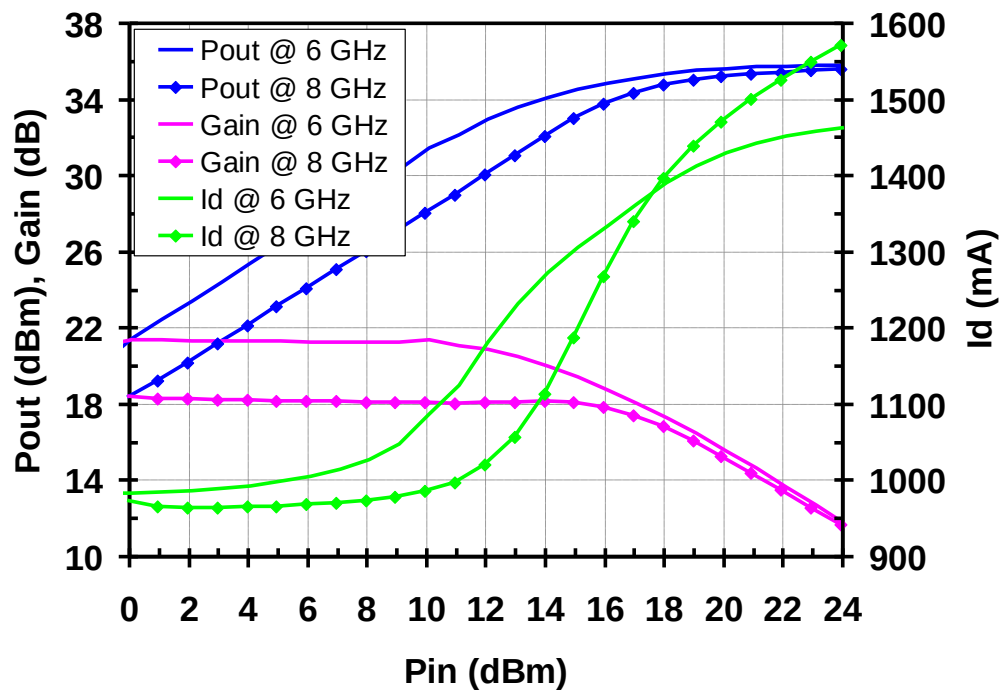
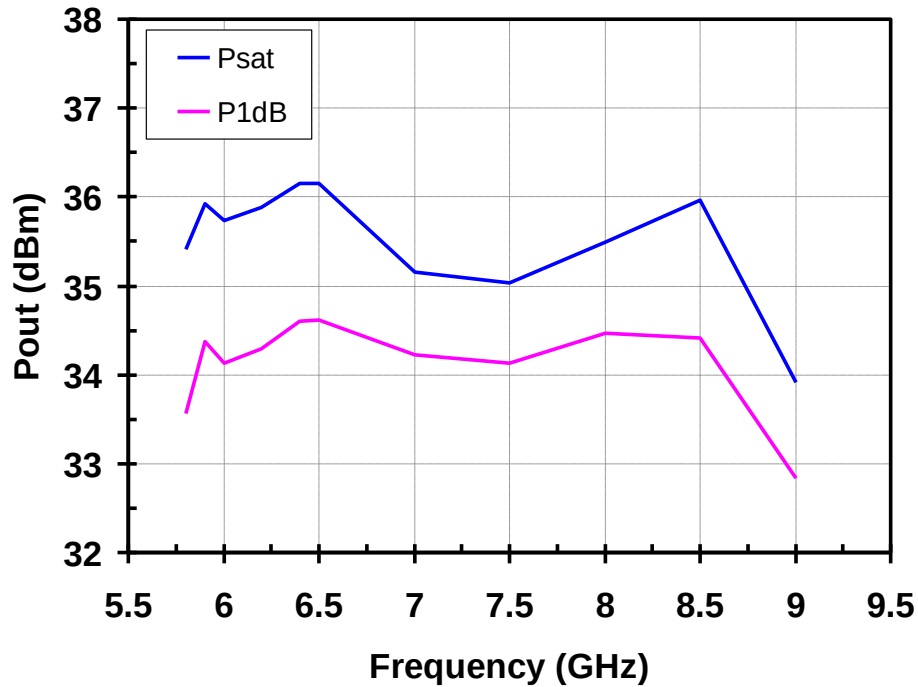
Performance Plots, Small Signal

Bias conditions: $V_D = 6\text{ V}$, $I_D = 1000\text{ mA}$, $V_G = -0.6\text{ V}$ Typical, $25\text{ }^\circ\text{C}$



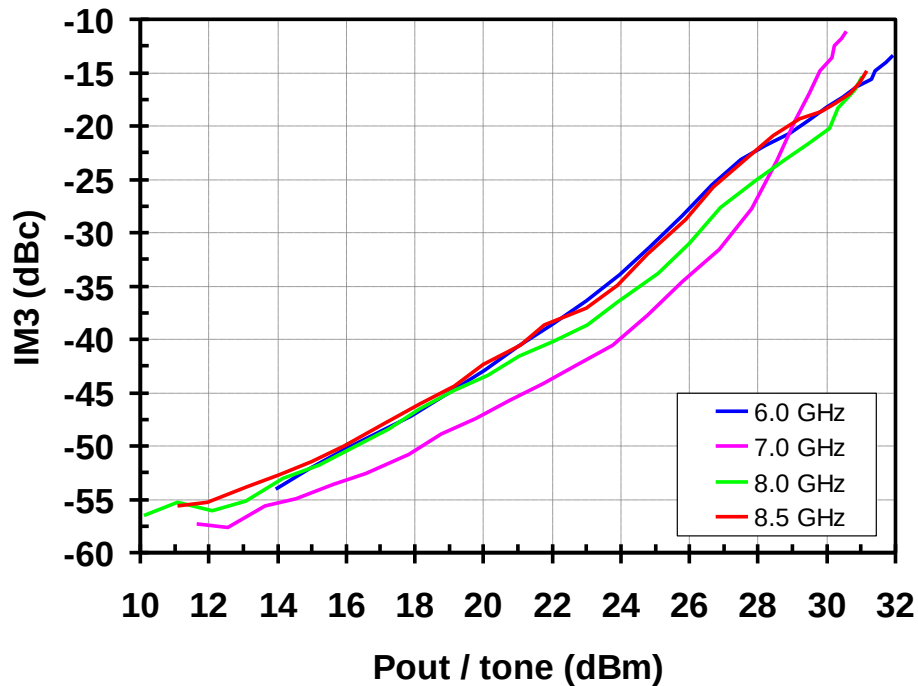
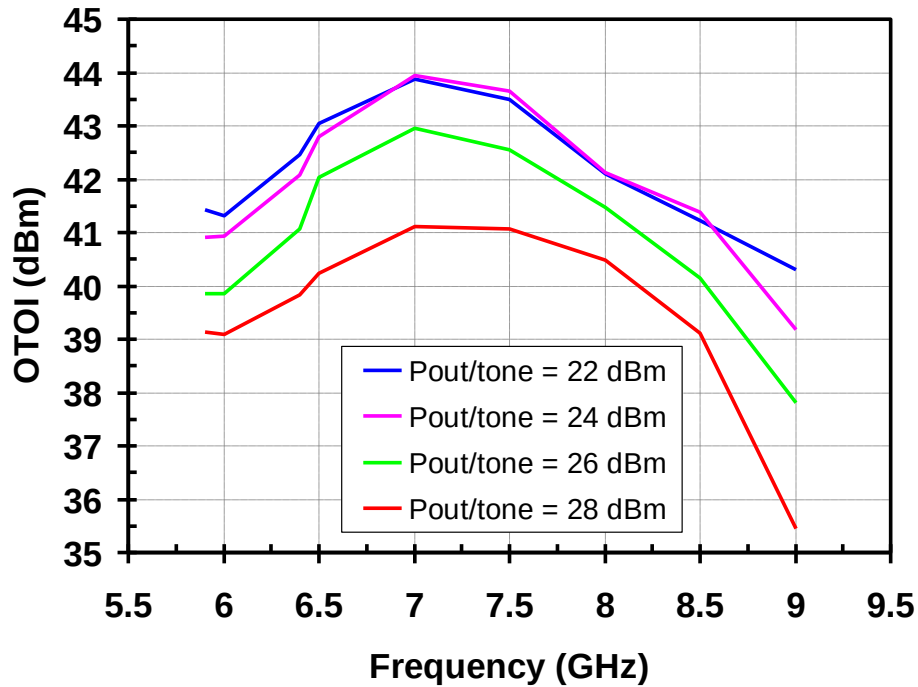
Performance Plots, Power

Bias conditions: $V_D = 6\text{ V}$, $I_D = 1000\text{ mA}$, $V_G = -0.6\text{ V}$ Typical, $25\text{ }^\circ\text{C}$



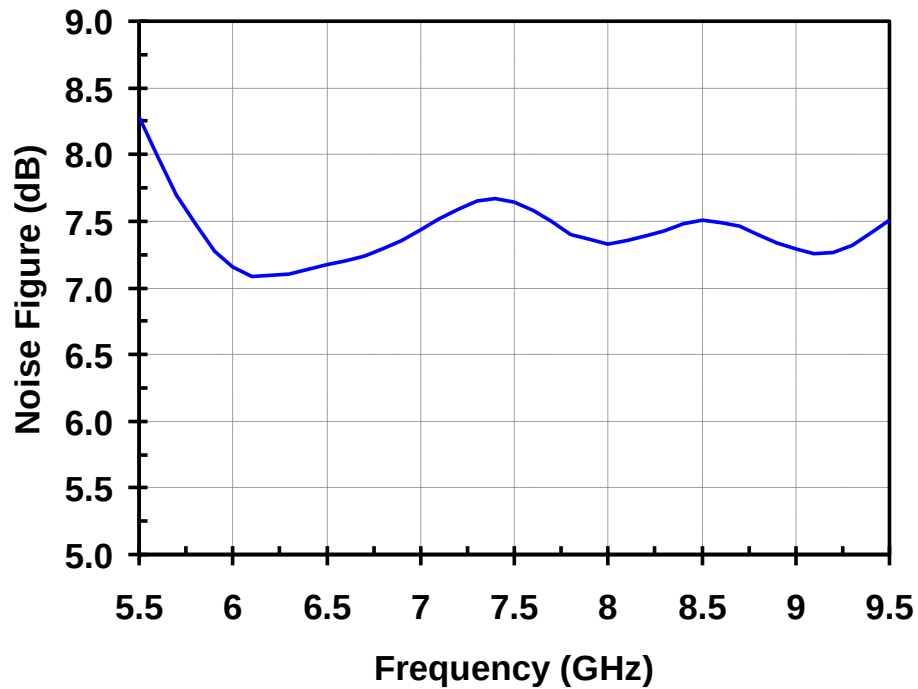
Performance Plots, Linearity

Bias conditions: $V_D = 6\text{ V}$, $I_D = 1000\text{ mA}$, $V_G = -0.6\text{ V}$ Typical, $25\text{ }^\circ\text{C}$



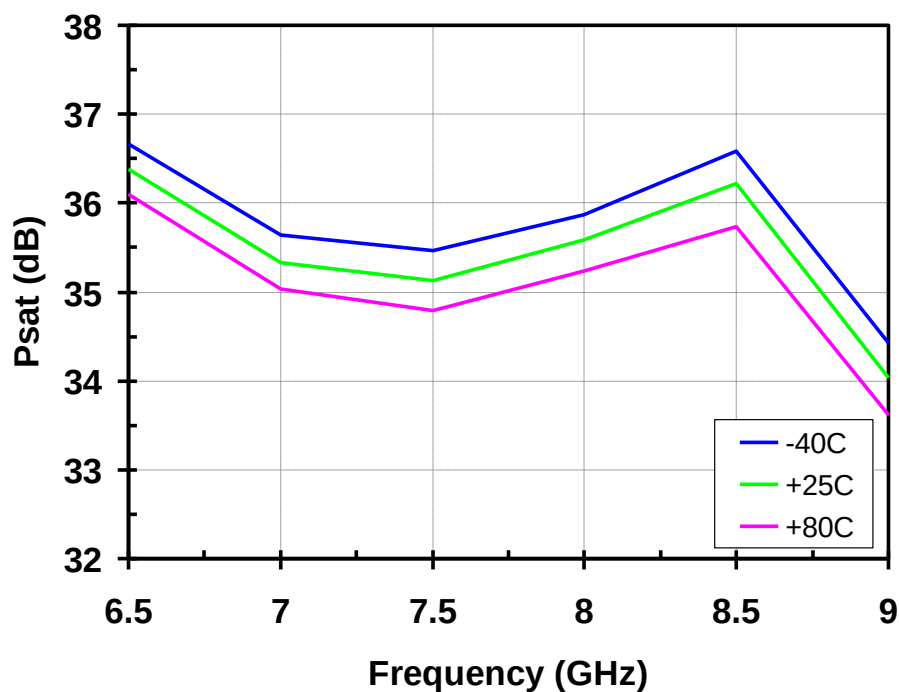
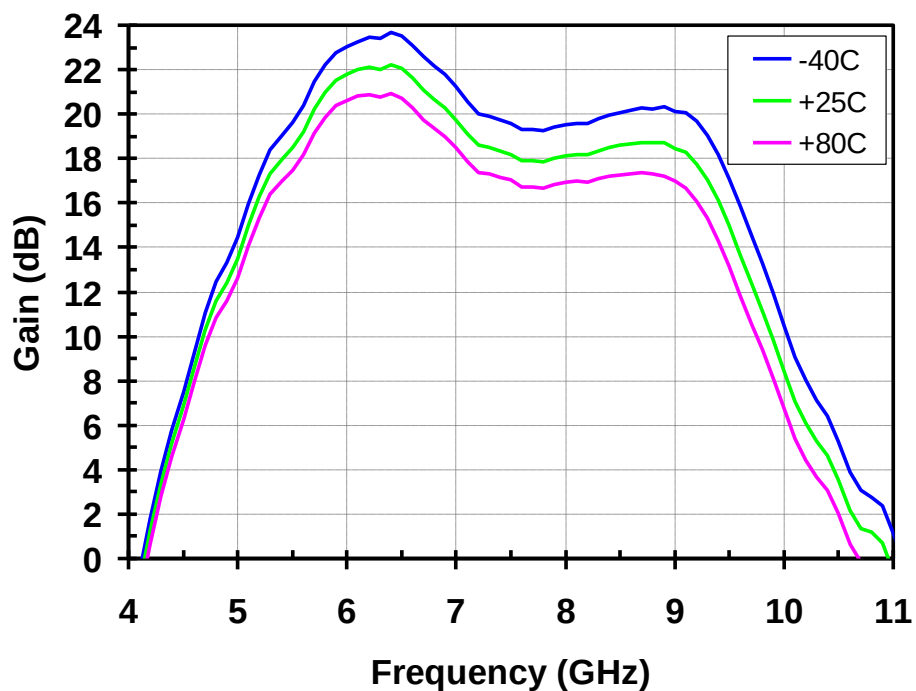
Performance Plots, Noise Figure

Bias conditions: $V_D = 6\text{ V}$, $I_D = 1000\text{ mA}$, $V_G = -0.6\text{ V}$ Typical, $25\text{ }^\circ\text{C}$



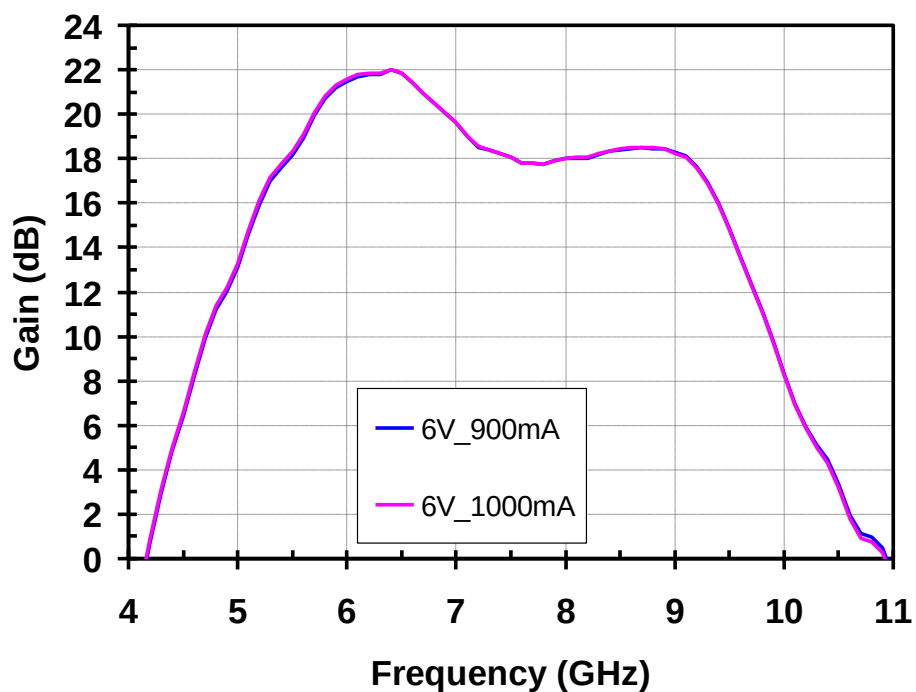
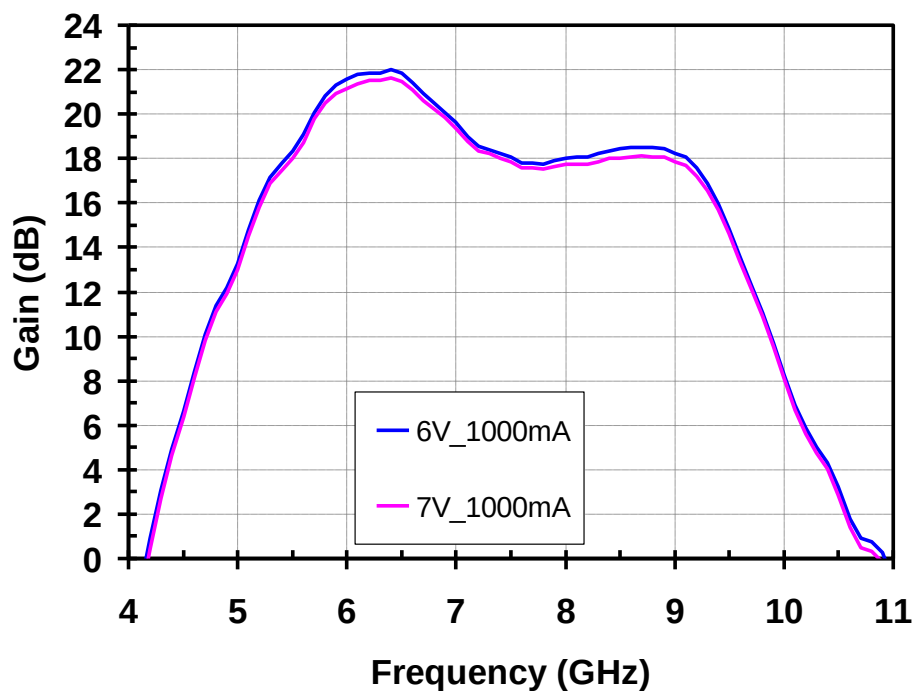
Performance Plots vs Temperature

Bias conditions: $V_D = 6\text{ V}$, $I_D = 1000\text{ mA}$, $V_G = -0.6\text{ V}$ Typical



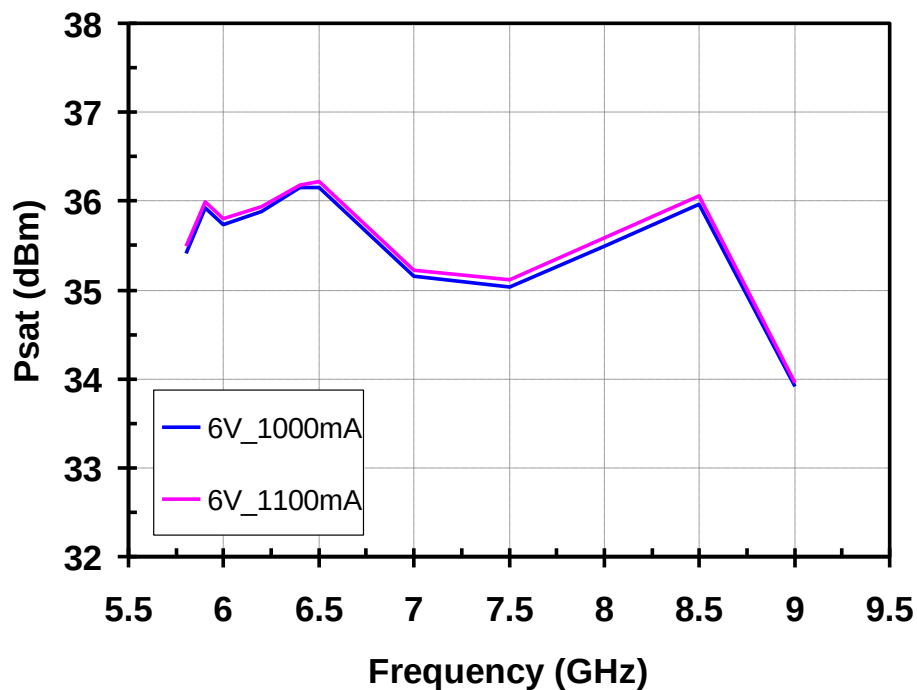
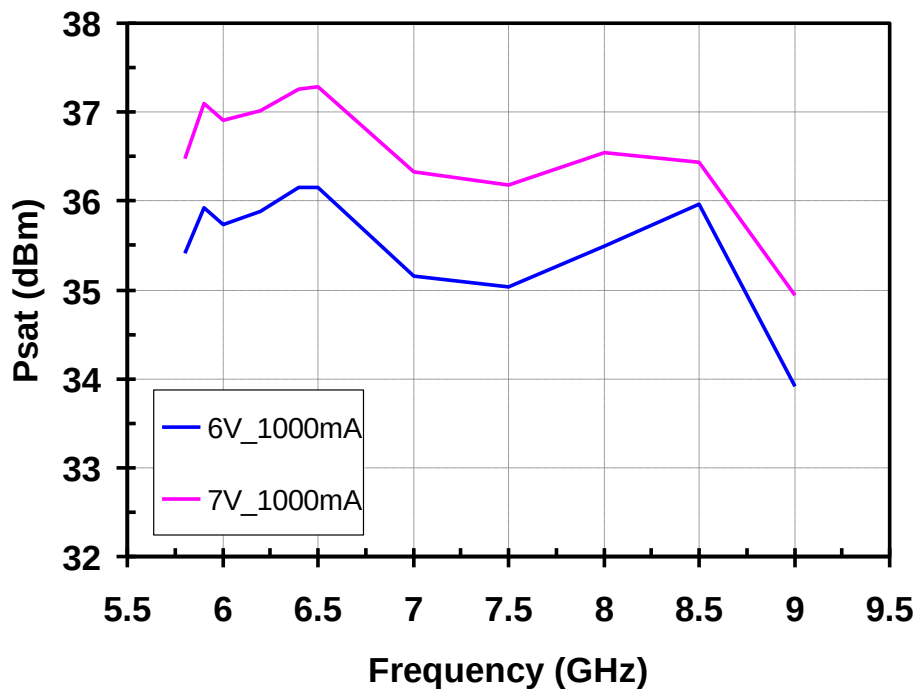
Small Signal Gain vs Bias

Bias conditions: Varies



Power vs Bias

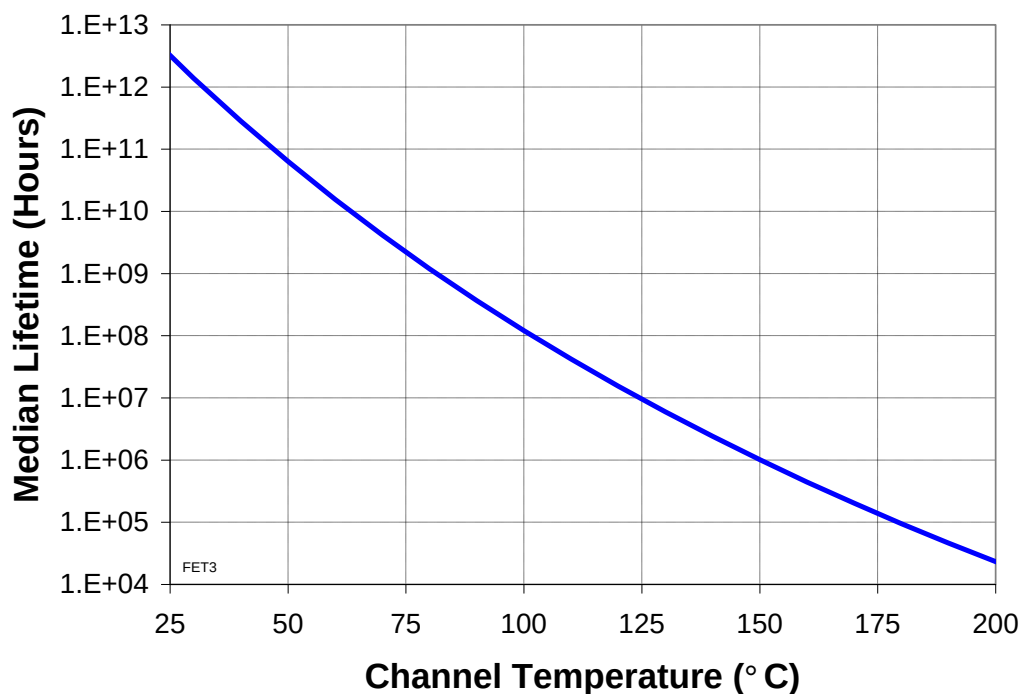
Bias conditions: Varies



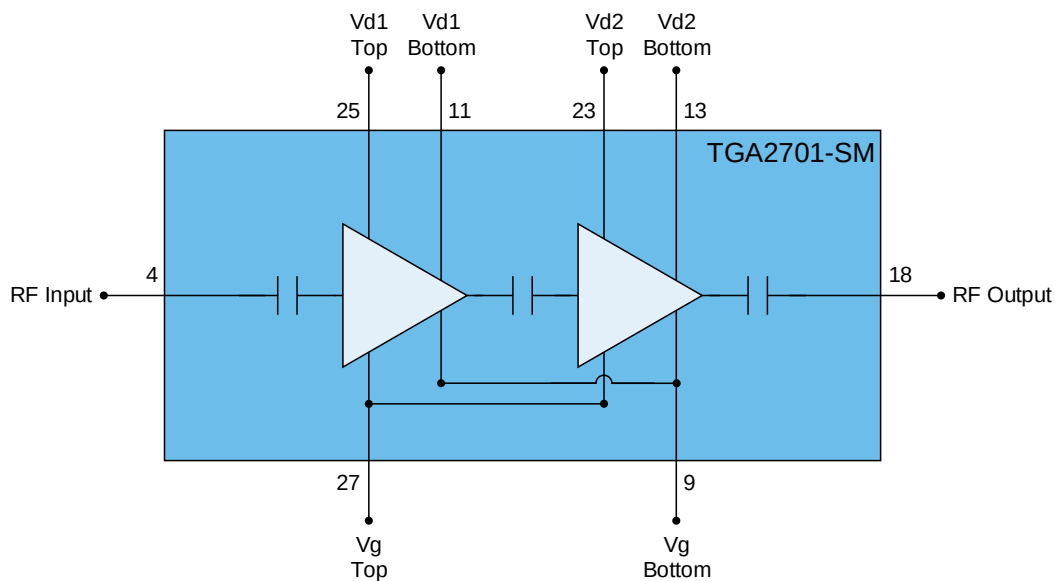
Thermal and Reliability Information

Parameter	Test Conditions	Value
Maximum Power Dissipation	$T_{\text{BASEPLATE}} = 85\text{ }^{\circ}\text{C}$	$P_D = 18.5\text{ W}$ $T_{\text{channel}} = 200\text{ }^{\circ}\text{C}$
Thermal Resistance, θ_{jc}	$V_D = 6\text{ V}$ $I_D = 1\text{ A}$ $P_D = 6\text{ W}$ $T_{\text{BASEPLATE}} = 85\text{ }^{\circ}\text{C}$	$\theta_{jc} = 6.2\text{ }^{\circ}\text{C/W}$ $T_{\text{channel}} = 122\text{ }^{\circ}\text{C}$ $T_m = 1.3\text{E}+7\text{Hrs}$
Thermal Resistance, θ_{jc} Under RF Drive	$V_D = 6\text{ V}$ $I_D = 1.6\text{ A}$ $P_{\text{OUT}} = 35.5\text{ dBm}$ $P_D = 6\text{ W}$ $T_{\text{BASEPLATE}} = 85\text{ }^{\circ}\text{C}$	$\theta_{jc} = 6.2\text{ }^{\circ}\text{C/W}$ $T_{\text{channel}} = 122\text{ }^{\circ}\text{C}$ $T_m = 1.3\text{E}+7\text{ Hrs}$
Mounting Temperature		Refer to Assembly Note and Solder Reflow Profiles
Storage Temperature		-65 to 150 $^{\circ}\text{C}$

Median Lifetime (T_m) vs. Channel Temperature



Electrical Schematic



Bias Procedures

Bias-up Procedure

V_G (combined V_{G_Top} & V_{G_Bottom}) set to -1.2 V

V_D (combined all four V_D) set to +6 V

Adjust V_G more positive until I_{DQ} is 1 A.

This will be $\sim V_G = -0.6$ V

Bias-down Procedure

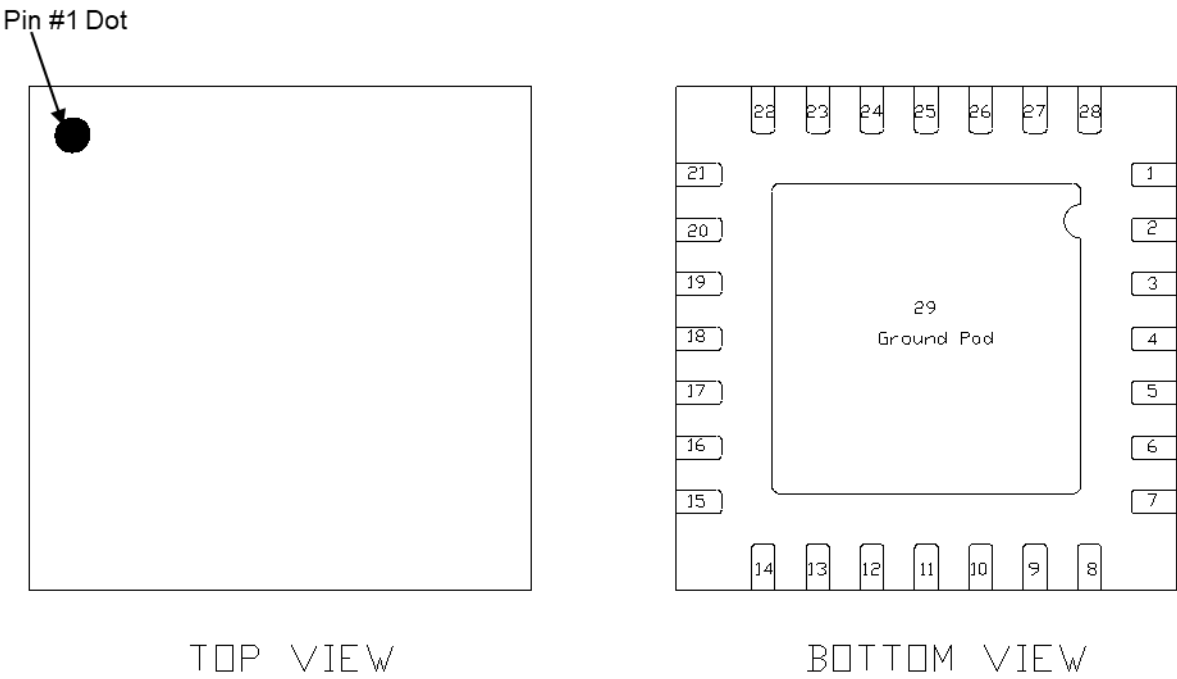
Turn off RF signal

Reduce V_G to -1.2 V. Ensure $I_d \sim 0$ mA

Turn V_D to 0 V

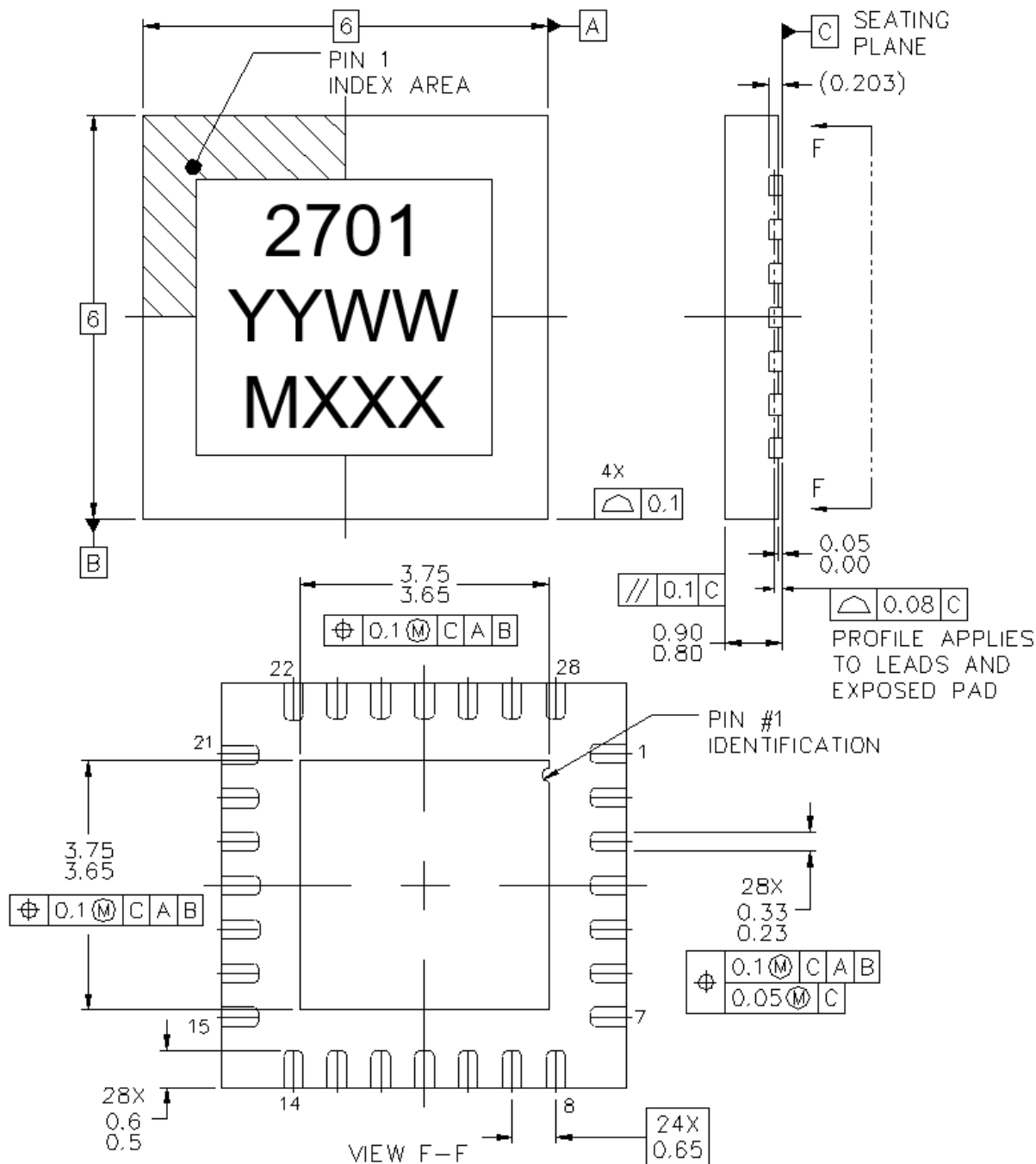
Package Pin Assignments

Package Pinout



Pin	Description
4	RF Input, DC blocked
9	V _G _Bottom
11	V _{D1} _Bottom
13	V _{D2} _Bottom
18	RF Output, DC blocked
23	V _{D2} _Top
25	V _{D1} _Top
27	V _G _Top
29	Ground
1, 2, 3, 5, 6, 7, 8, 10, 12, 14, 15, 16, 17, 19, 20, 21, 22, 24, 26, 28	No internal connections

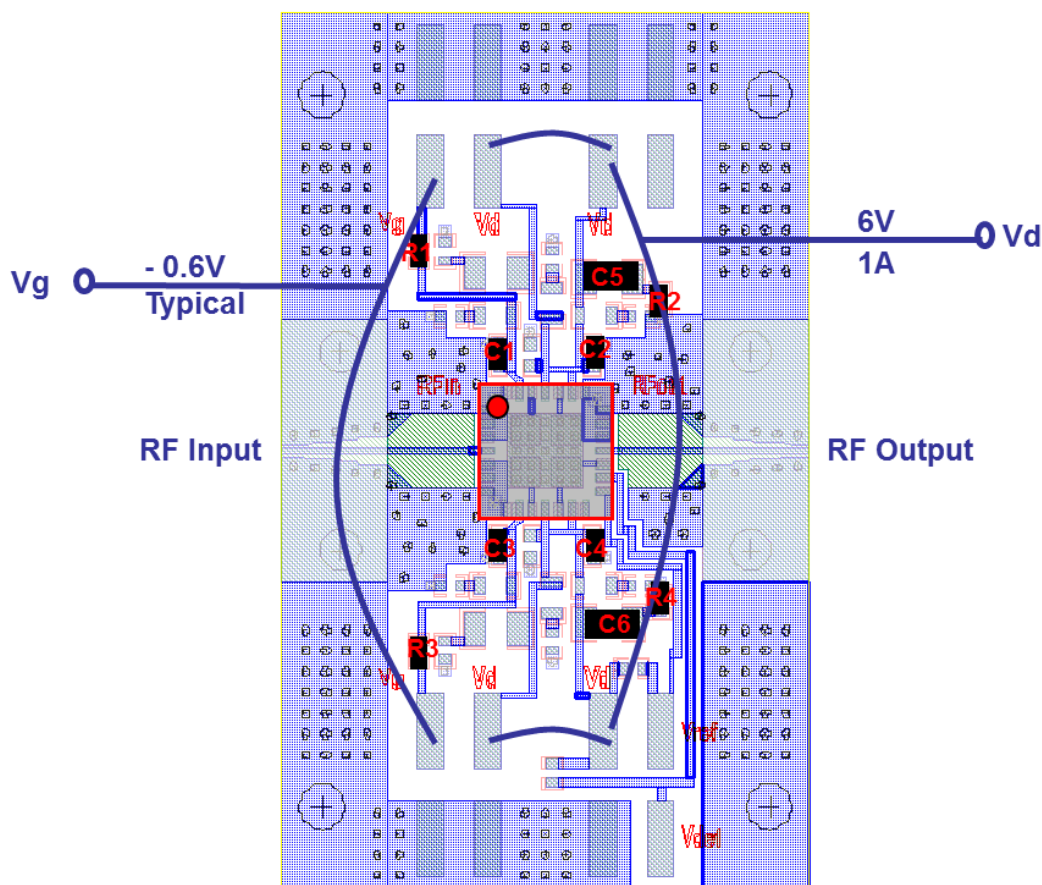
Mechanical Drawing



Notes:

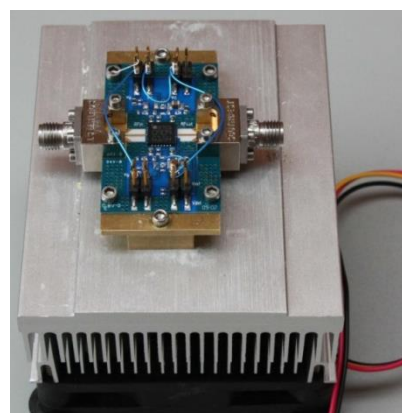
1. Dimensions in mm
2. The package is mold encapsulated with NiPdAu plated leads.
3. Package Marking: 2701: Part Number, YY = Part Assembly Year, WW = Part Assembly Week, MXXX = Batch ID

Recommended Assembly Board



Part	Description
C1, C2, C3, C4	1000 pF Capacitor (0402)
C5, C6	1 uF Capacitor (0805)
R1, R2, R3, R4	0 Ohm Resistor Jumper (0402)

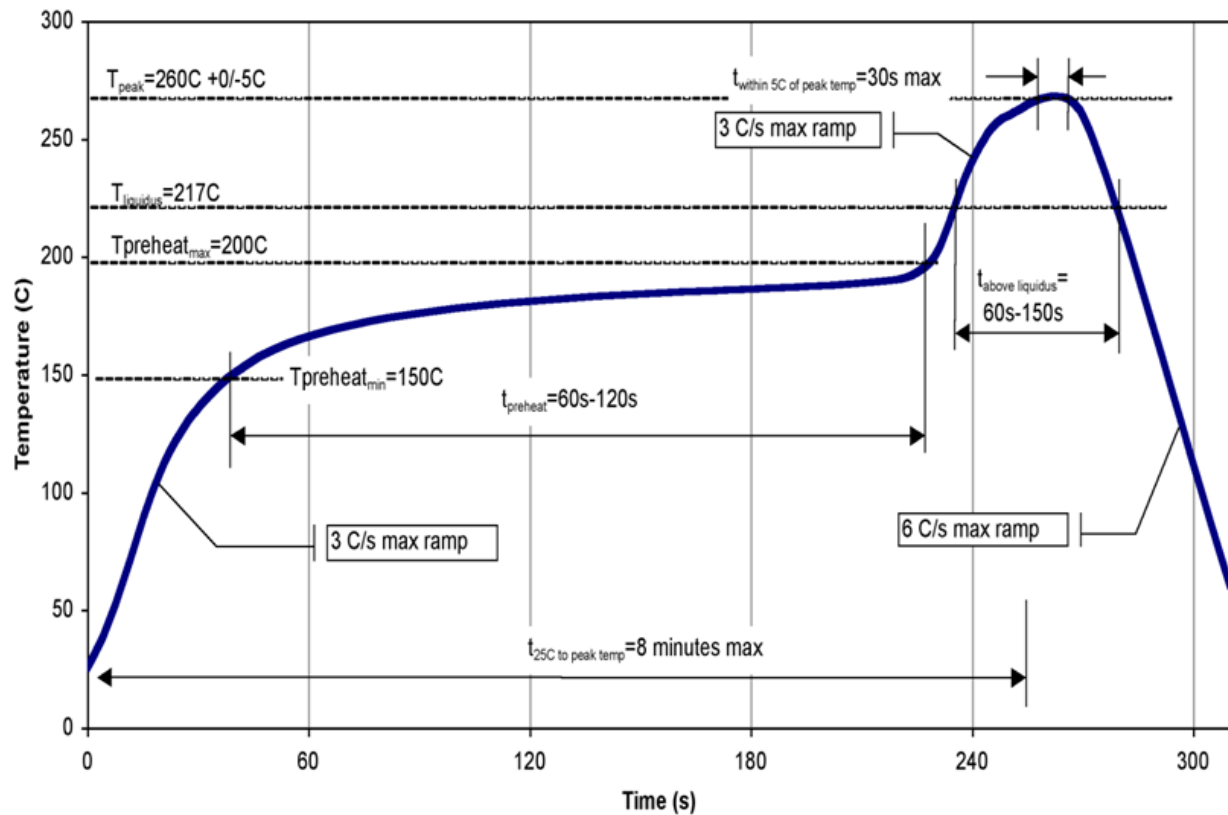
Board is 8 mil thick RO4003 with 1oz copper cladding.
Board is mounted on metal block and adequate heatsinking with fan is required.



Solderability

1. Compatible with the latest version of J-STD-020, Lead-free solder, 260 °C.
2. The use of no-clean solder to avoid washing after soldering is recommended.

Recommended Soldering Temperature Profile



Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	TBD	ESDA / JEDEC JS-001-2012
ESD – Charged Device Model (CDM)	TBD	ESDA / JEDEC JS-002-2014
MSL – Convection Reflow 260 °C	3	JEDEC standard IPC/JEDEC J-STD-020



Caution!
ESD-Sensitive Device

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Qorvo:

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Tel: 1-844-890-8163

Email: customer.support@qorvo.com

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